

LAMINATED SHEET FOR PACKAGING ELECTRONIC COMPONENT AND MOLDED BODY THEREOF

ABSTRACT

The present invention discloses a laminated sheet for packaging electronic components comprising a front surface layer, a center core layer and a rear surface layer, wherein the front surface layer and the rear surface layer each contains a rubber-modified styrenic copolymer (A) having a graft ratio of grafted rubber of 30 to 50%, a grafted rubber particle diameter of 0.1 to 0.5 μm and a butadiene content of 5 to 25% by weight, and polyetheresteramide (B), and the center core layer contains a rubber-modified styrenic copolymer (C) having a graft ratio of grafted rubber of 70 to 90%, a grafted rubber particle diameter of 0.4 to 1.0 μm , and a butadiene content of 5 to 15% by weight, and 5 to 50 % by weight of a recycled material of this laminated sheet. The laminated sheet is well balanced in physical properties such as antistatic properties, transparency, folding strength, etc., and even if a recycled material is added to the center core layer, visibility in the inspection through a carrier tape is favorable, and thus, the laminated sheet can be preferably used for preparing a sheet for packaging electronic components, such as embossed carrier tape, etc.

No Figure